

I-T Tables and BIRD42.3 Revisited

Bob Ross
Teraspeed Consulting Group

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Some IBIS Summit Presentations Regarding Power Rails for SSN and I-T

- See IBIS home page Articles, summits on the eda.org IBIS summits site
- Raymond Chen, Sigrity: Feb. 2004 (add Cdie)
- Bernhard Unger, Siemens: Jan. 2000 (adds Cpre and adjustment for rail collapse)
- Ambrish Varma, NCSU: June 2004 (simultaneous switching noise and rail collapse)
- Norio Matsui, Applied Simulation Technology: Jan. 2001 (LSI power and ground model for EMI simulation with internal clock and paths)
- Etienne Sicard, INSA: Sept. 2001, Sebastien Calvet INSA Jan. 2002 (chip core I-T model for EMI)
 - I-T source for supplies derived from statistical switching model simulations (with AMS or SPICE or simplified SPICE)
 - Part of ICEM model and IC-Emit freeware (Feb. 20, 2004)
 - Can be modeling using multi-lingual extensions
- C. Kumar, Cadence: Jan., Feb. 1998, Bob Ross Feb. 1998: (I-T tables in buffers and BIRD42.3)

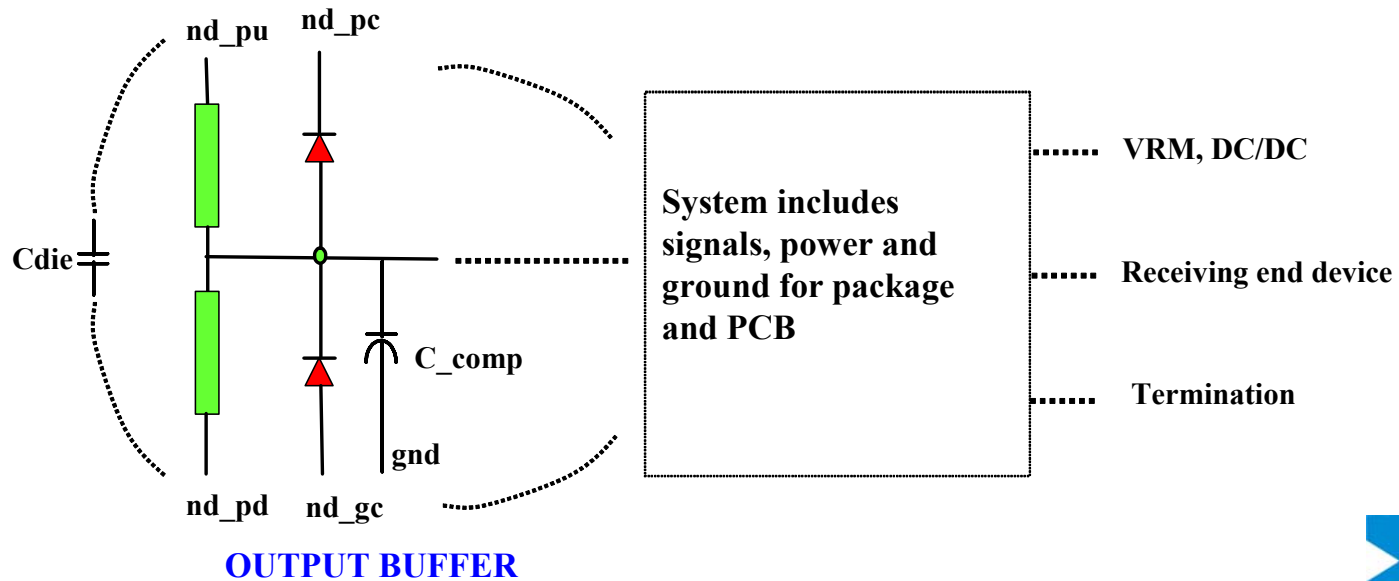


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Adding Cdie (Chen, February 2, 2004)

After Adding Cdie

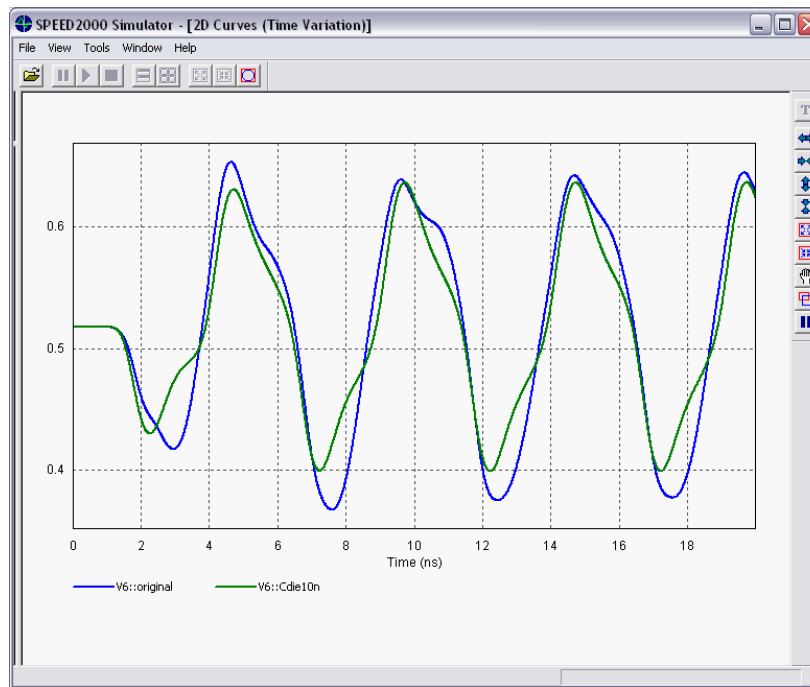
1. Driver end waveform will be more accurate.
2. Noise simulation will be more accurate, for example, power and ground noises at die pad.



Chen, Continued

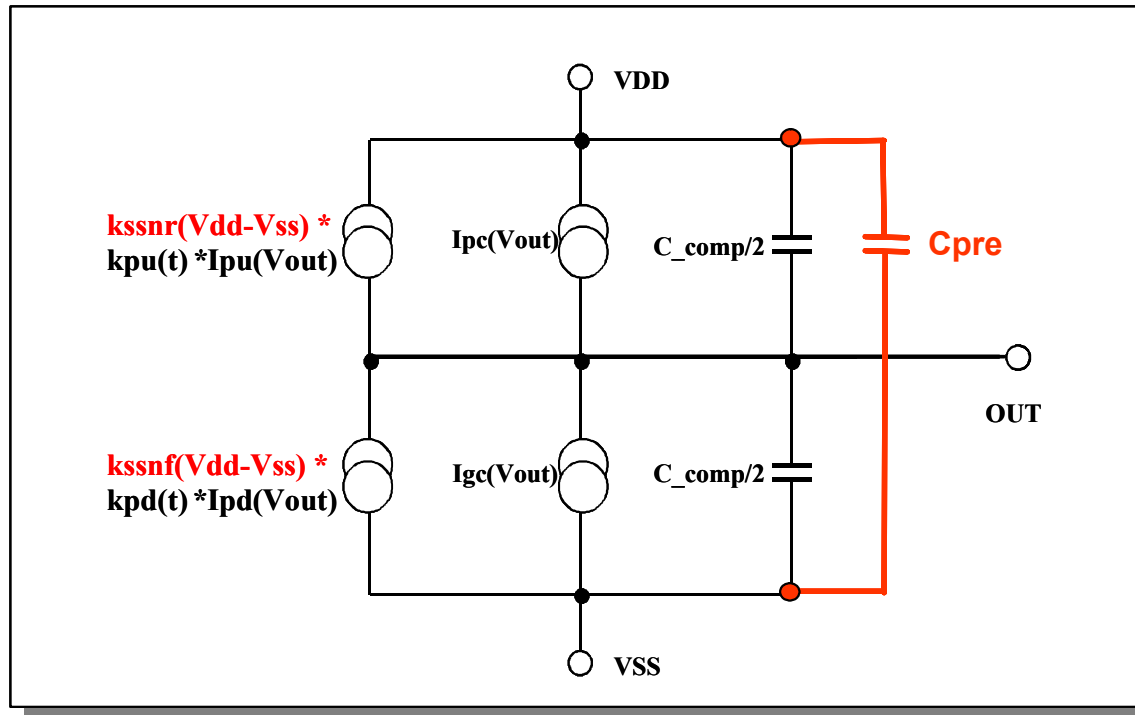
After Adding Cdie

1. With a few nF Cdie, victim line (stuck low) at the board receiver end shows less noise.



Rail Collapse Adjustment (Unger, January 31, 2000)

Enhanced two Waveform Behavioral Model
including prestage Vdd-Vss Capacitance



$Cpre$:
Vdd-Vss prestage
Capacitance

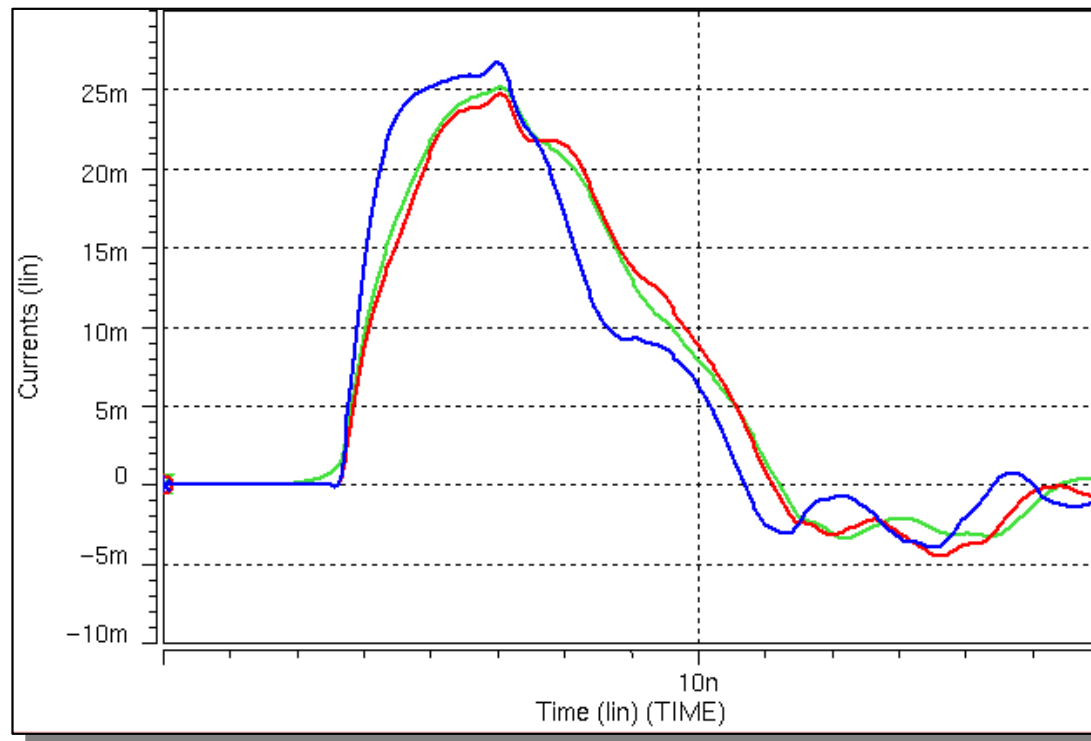
Evaluation:
SPICE simulation
using a capacitance
bridge

Unger, Continued

BD4 SSN analysis results (rising edge)

Vdd current of 1 bd4 buffer

Number of SSO = 10



Supply currents:

Transistor based

Enhanced behavioral
including prestage C

Usual behavioral



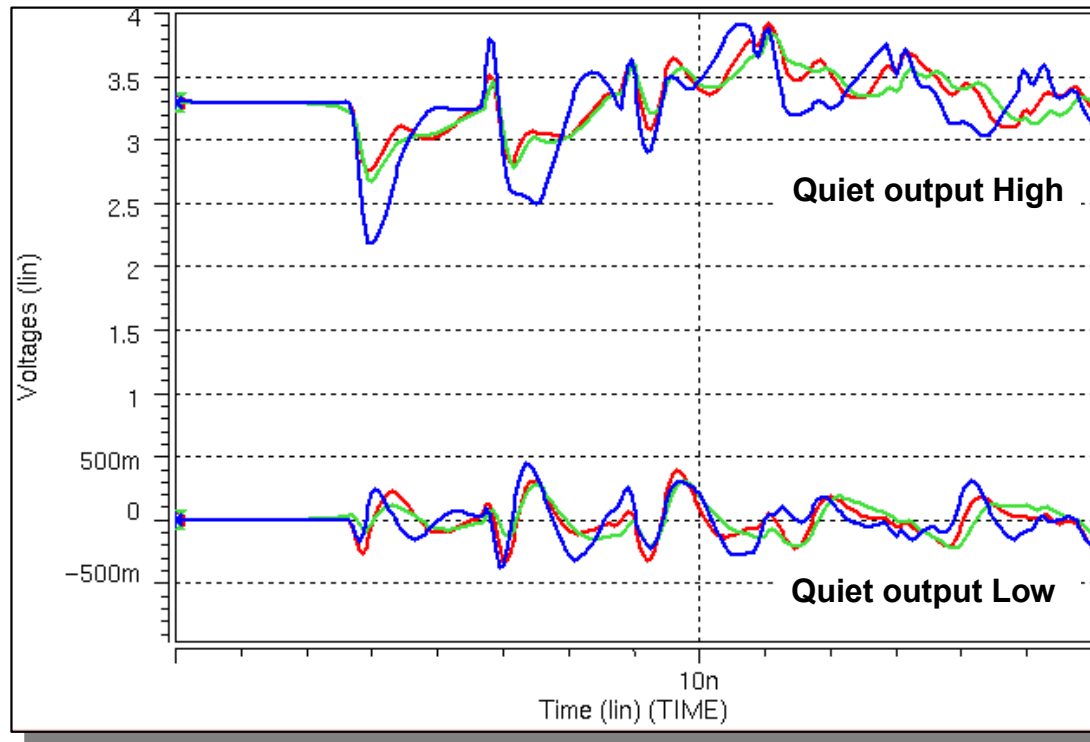
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Unger, Continued

BD4 SSN analysis results (rising edge)

Noise on quiet outputs

Number of SSO = 10



Quiet output signals:

Transistor based

Enhanced behavioral
including prestage C

Usual behavioral

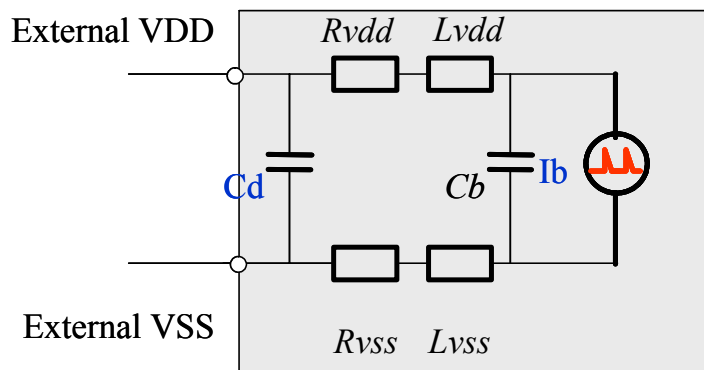


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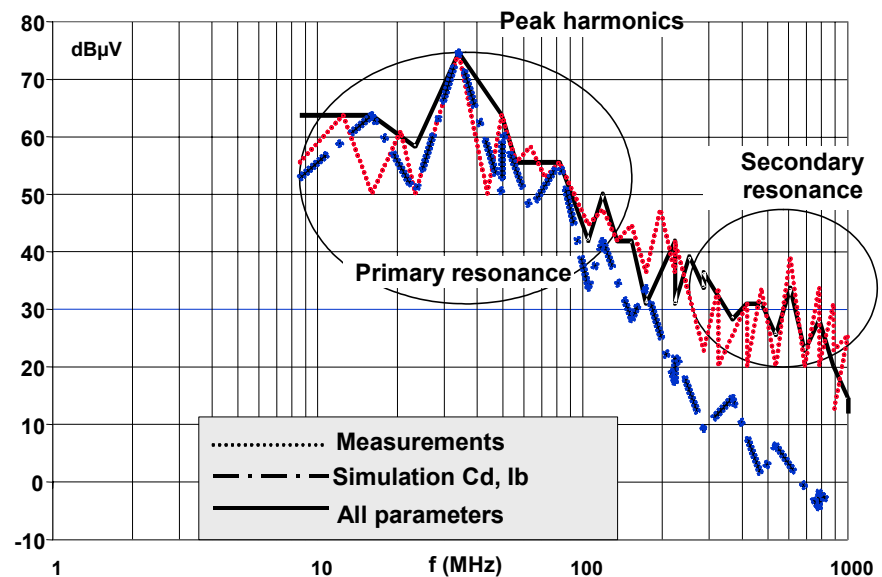
Core Emission I-T Model for EMI (Calvet, Jan. 28, 2002)

4. Core Emission Model

ICEM includes a simple core model, not handled by IBIS



Basic parameters	Cd, Ib
Advanced param.	R,L,Cb

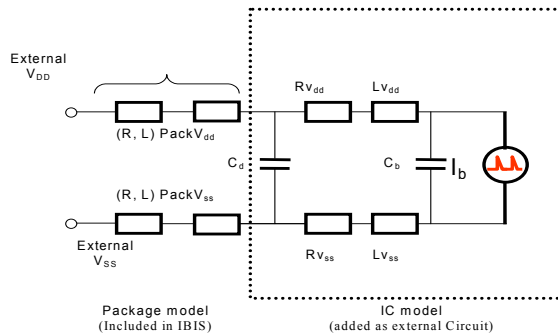


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Core Model I-T Emission Models as Multi-Lingual SPICE Extension of IBIS

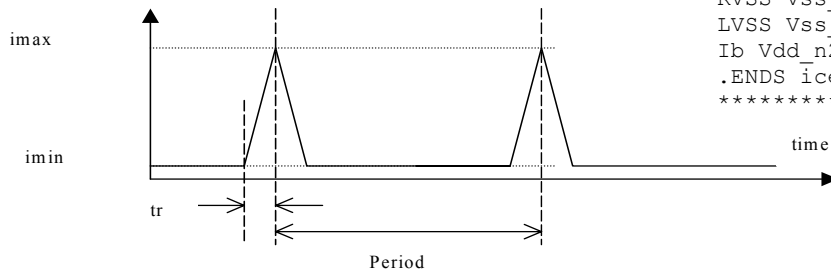
68HC12 D60

ICEM MODEL



L_{PackV_{ss}}=2.2nH
 L_{PackV_{dd}}=2.2nH
 C_d=3.2nF
 R_{vss}=2
 R_{vdd}=2
 C_b=50pF

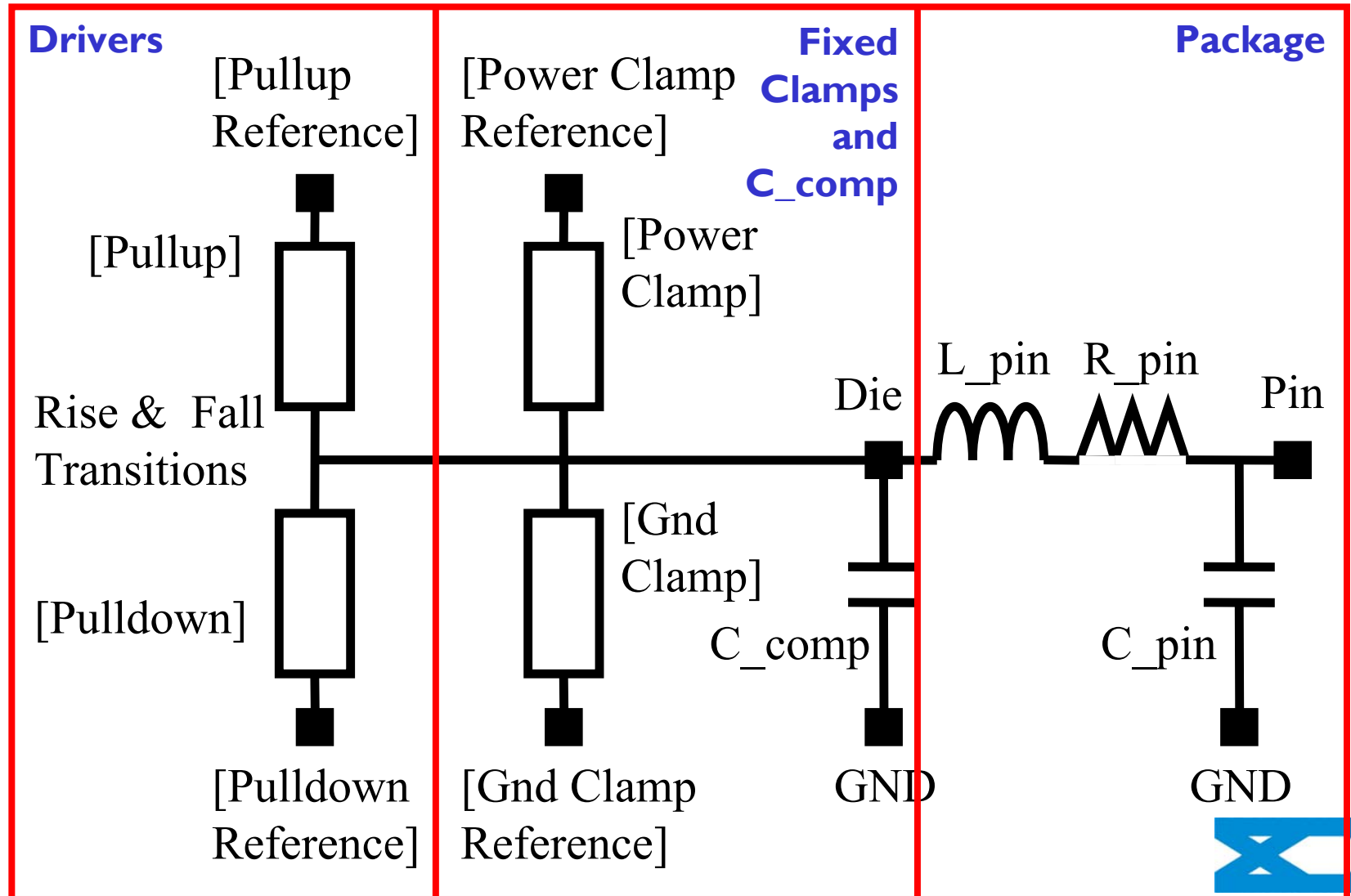
Current generator Ib



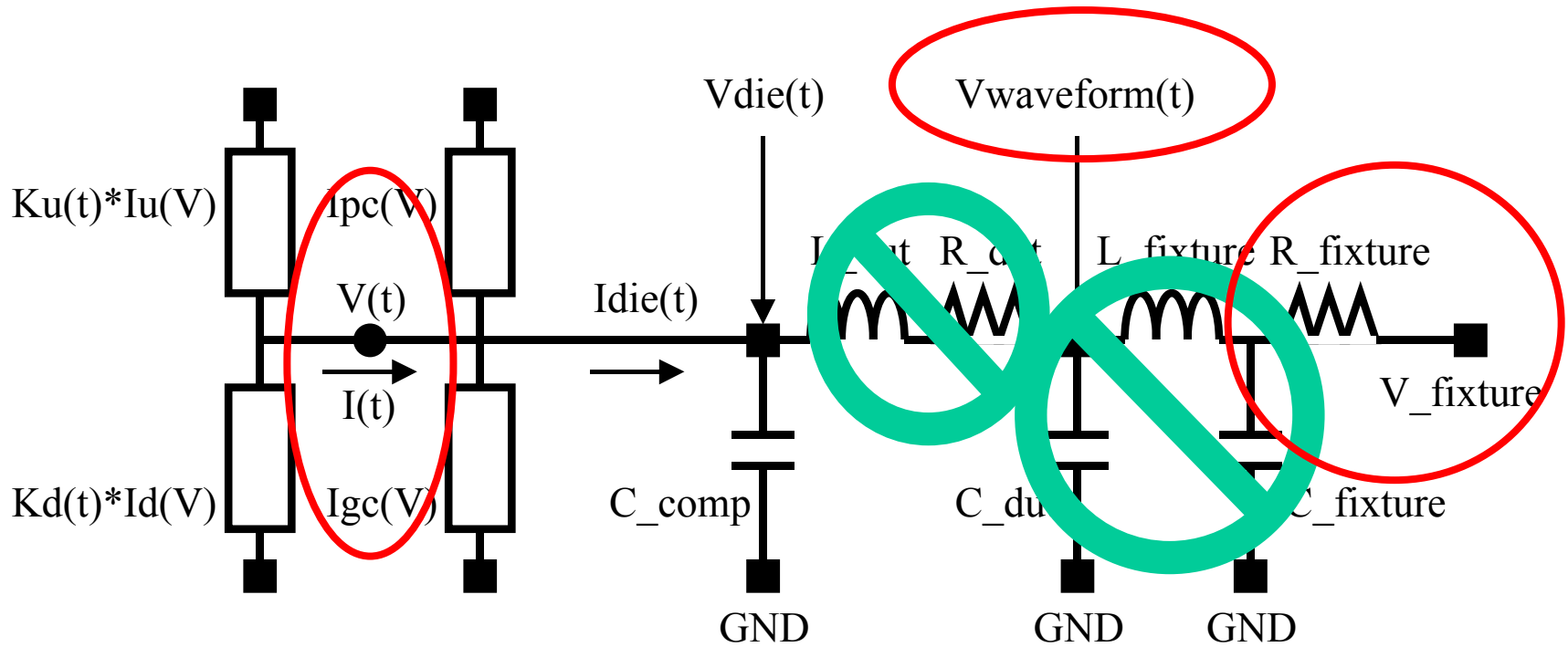
Period = 31.25ns.
 Imin = 0.01A
 Imax = 0.4A
 Tr = 1ns

```
| Some additions to the IBIS model:
| *****
| [Circuit Call] ICEM
| mapping port      node
| Port_map  vdd_ic  12
| Port_map  vss_ic  14
| [End Circuit Call] | Code connecting 12 to 65 and 14 to 66 on the die
|                   | is not shown
| *****
| [External Circuit] ICEM
| Language SPICE
| | Corner      corner_name  file_name  circuit_name (.subckt name)
| | Corner      Typ          icem_d60.spi  icem_typ
| | Ports are in same order as defined in SPICE
| Ports        vdd_ic      vss_ic
| *****
| * Separate SPICE file icem_d60.spi
| *****
| .SUBCKT icem_typ vdd_ic vss_ic
| RVDD Vdd_ic Vdd_n1 2
| LVDD Vdd_n1 Vdd_n2 2.2n
| Cd Vdd_ic Vss_ic 3.2n
| Cb Vdd_n2 Vss_n2 50p
| RVSS Vss_ic Vss_n1 2
| LVSS Vss_n1 Vss_n2 2.2n
| Ib Vdd_n2 Vss_n2 PULSE(0.01 0.4 10ns 1.0ns 1.0ns 0.01ns 31.25ns)
| .ENDS icem_typ
| *****
```

BIRD 42.3 - IBIS 2.1 Buffer Model



V-T Tables and Fixture Loads to get $K_u(t)$, $K_d(t)$ for Rise, Fall Edges

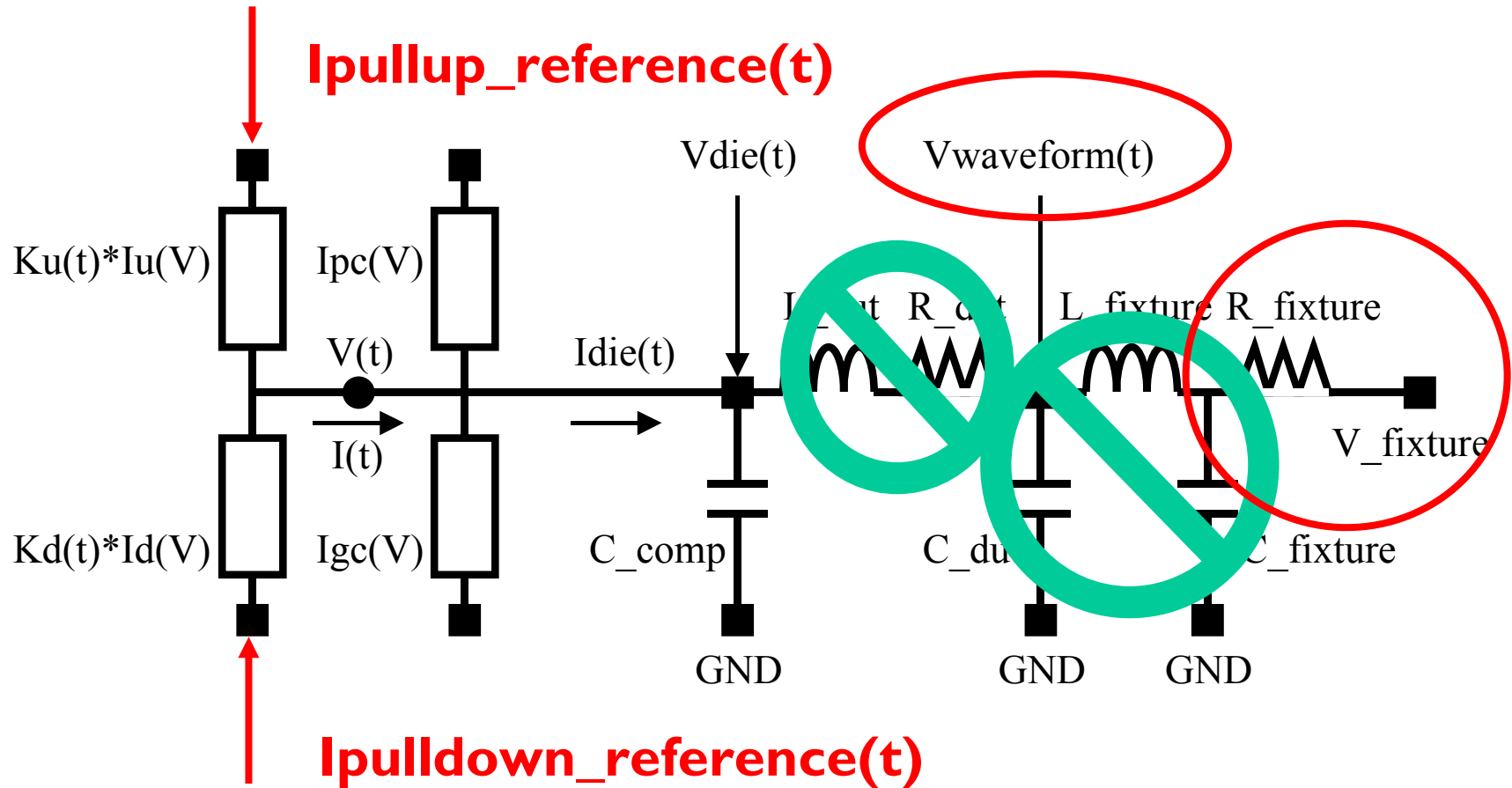


Recommended Loads:

50 Ω to Vcc

50 Ω to Gnd

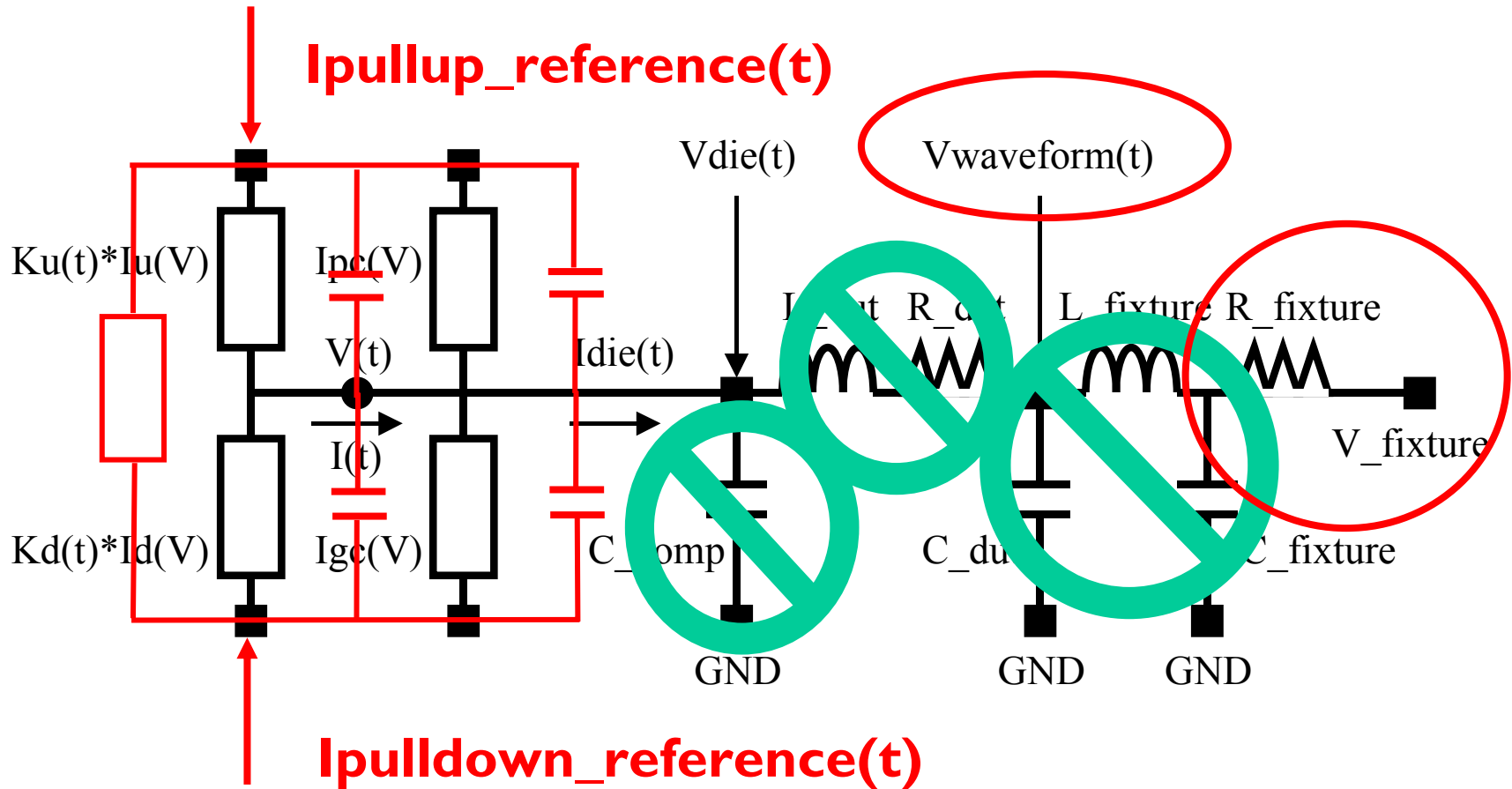
BIRD42.3 Proposal (V-T and I-T tables)



(0, 1, or 2 current tables allowed)

Current Definition Problem?

EDA Spec., Processing Ambiguity



(0, 1, or 2 current tables allowed)

BIRD42.3 Assumptions and Limitations

- Adds V-T and I-T PAIRS for a given fixture load
 - Under [Rising Waveform] or [Falling Waveform] table
 - Keep V-T table and its fixtures
 - [Pulldown Reference Current], [Pullup Reference Current] tables (None, both, or either - such as one easiest to isolate)
 - Could support Open_drain, Open_source and ECL models
- Currents might need to be separated from clamps or other current paths in the model
 - Permanent (internal terminator “clamps”)
 - Individual capacitance to each rails
 - Very complex for tools to automatically do this



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Some Format Considerations

- Referenced to driver rails since clamps are optional, and clamp currents hard to isolate
- Extension limitations may exist
 - Driver Schedule – rails not necessarily common or inherited, nor currents easily allocated to scheduled models
 - Submodels – same rails, but triggered internal behavior needs triggered I-T data
 - True differential buffer current allocation not considered
 - ECL Pullup Reference Current allocation/algorithm issue



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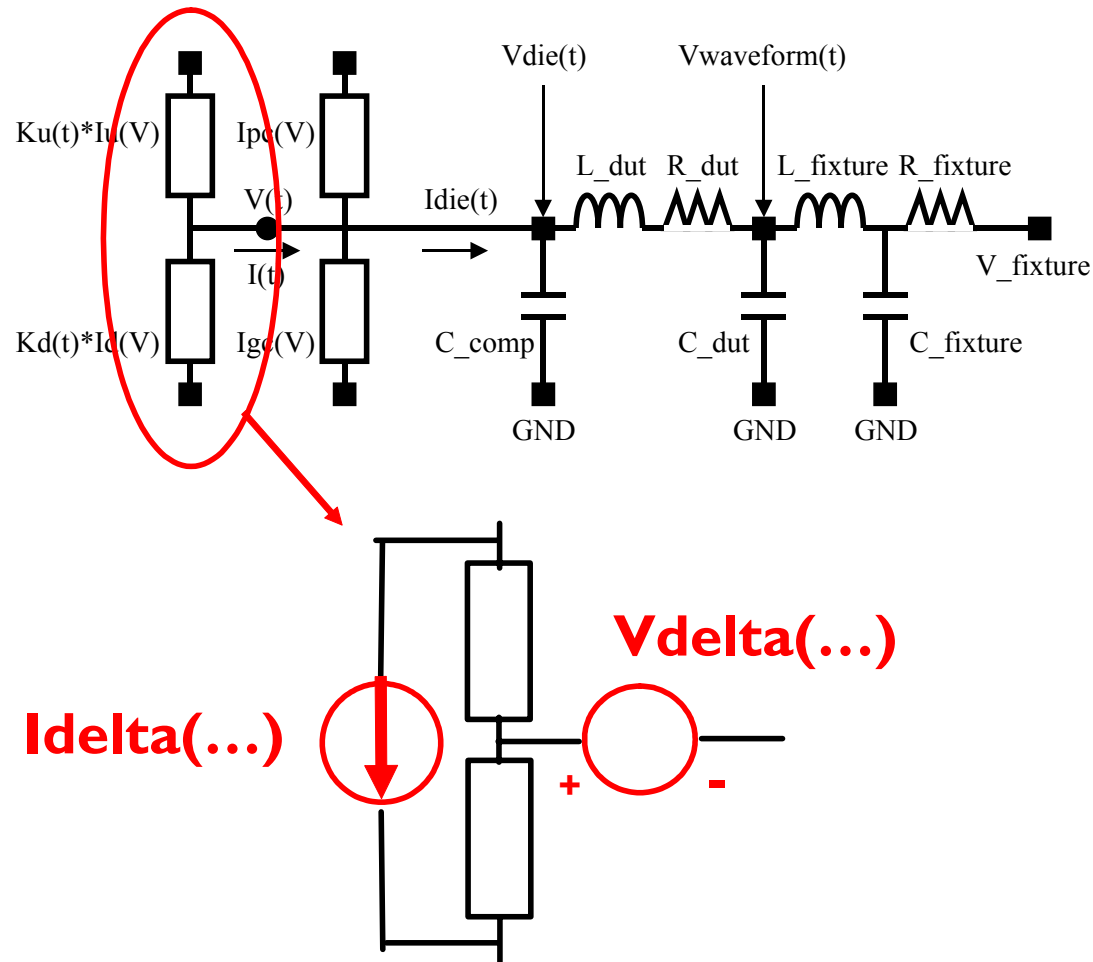
EDA Tools: Several Choices for Over-specified Cases

- Voltage based solution option
 - Use the V-T table information first for V-T data matching via existing $K_u(t)$, $K_d(t)$ extraction methods
 - May not capture as accurately the rail currents
- Current based solution option
 - Use the current information first (more direct solution of $K_u(t)$ and $K_d(t)$ with excess common “crowbar” currents)
 - But not match the V-T data as well
- Augmented model for voltage and current matching
 - Adds $I_{\Delta}(\dots)$ and $V_{\Delta}(\dots)$ variables for more matching options and strategies
 - (E.g., match V-T tables, then match currents with I_{Δ})
 - $I_{\Delta}()$, $V_{\Delta}()$ could be a function of I_u and I_d currents
 - More research needed



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Augmented Model (Ross, Feb. 26, 1998)

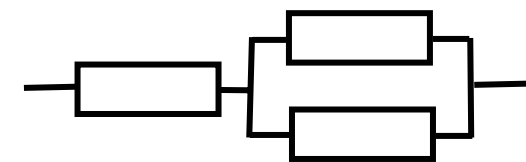
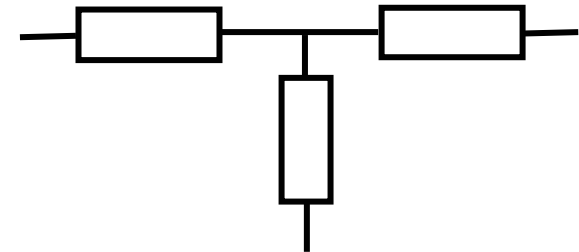
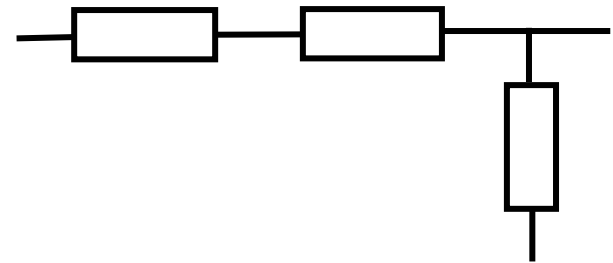


I-T Extraction Issues

- SPICE based (most practical)
 - Still must carefully isolate rail currents and then post-process them to fit topology
 - Can use ideal current sense mechanism (0 V voltage sources)
 - Still may deal with fast current edges and spikes
 - Best R_fixture, V_fixture choices need to be investigated for overall accuracy (V_fixture = GND, Vcc, Vcc/2, etc.)
- Measurement based (many issues and may be impractical)
 - Includes the package
 - Current probe bandwidth & impedance vs. 50 ohm measurements
 - Or standard 1 ohm test load distortion
 - Several buffers on same power line
 - Unrelated currents from non-driver circuits

Package Model for Supplies (not explicit in IBIS)

- $R_{pin} - L_{pin} - C_{pin}$
 - Implied, but puts C_{pin} across voltage source
 - Could be distributed model (small T-line)
- $R_{pin} - C_{pin} - L_{pin}$
 - C_{pin} to reference rail, to ideal GND or across
 - L_{pin} to V_{cc}
 - Moves C_{pin} from rail



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Summary and Observations

- BIRD42.3 explained
 - Issues and compromises to fit in IBIS
 - EDA simulation options
- Other approaches given
 - SSN model extensions
 - Core I-T models for ICEM
- What is the problem?
 - Simultaneous switching noise of selected buffers?
 - Board power distribution issues and internal core noise?
- Do I-T tables help solve the problem?
 - I-T IBIS buffer extension or other proposals?
 - Multi-lingual extensions?
 - EDA tool support?



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